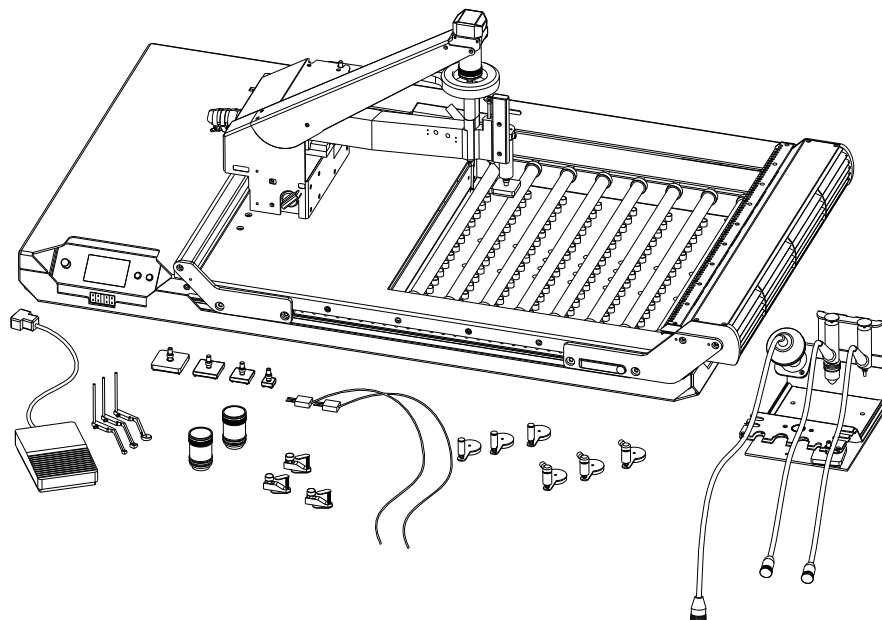


EXPERT 10.6-HXV


Rework Station with 5000W hybrid under heater. The heating area of 450x420mm² is adjustable to PCB size . Automated SMD placement process by Auto Vision Placer (AVP) incl. Easy Solder software package and DBL 06 control unit with six high resolution sensors inputs for thermocouples (Type K).

This system is particularly suitable for large size PCBs like PCs, Laptops and Server Boards with small up to very big components.

Standard Equipment (Art.No. DB00.1066)






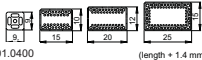



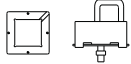


- Tool set for dispensing, placing, residual solder removal and soldering with magazine
- Set of placement nozzles XL-type (BGA/CSP) 5mm, 8mm, 15mm with O-Ring
- Set of solder nozzles (BGA) 15mm, 27mm, 35mm, 40mm
- Two camera lenses (BGA und CSP)
- Two thermo couple sensors (type K)
- Six PCB magnet holders 40,5mm (3xstandard, 3xEasy Lock)
- Three PCB clips to install at hand rest
- Foot switch
- Rework ABC and manual

Technical Data

System power consumption:	5500 VA	
Power solder pen:	300 W, 35 l/min	
Power underheater:	1200 - 5000 W, 8 x IR lamps	
Effective heating area:	450 x 420 mm ²	
Recommended max. PCB size	480 x 480 mm ²	
Resolution motion system:	0,001 mm	
Placement accuracy :	± 0,015 mm	(Flip Chip)*
	± 0,030 mm	(CSP)
	± 0,040 mm	(BGA)
	± 0,070 mm	(Maxi BGA)*
High resolution CMOS-camera:	5 Mio. Pixel, USB2	
Camera field of view (FOV):	22 x 16 mm ²	(Flip Chip)*
	42 x 32 mm ²	(CSP)
	57 x 42 mm ²	(BGA)
	96 x 71 mm ²	(Maxi BGA)*
Mains:	1 Phase, 230VAC, Fuse 25A	
	Connector Type CEE 32A (3 phase)	
Pressurized air:	5 - 8 bar, 100l/min	
	clean dry air	
Foot print:	1030 x 630 mm ²	
*Optional Extras		

EXPERT 10.6-HXV

Optional Extras

SF66.0002	Micro SMD nozzles and lens for AVP 4XL licence MS, 3 n, 3 solder n, lens FC	
DVSX.0007	Report with pcb identification for ES 05, licence RP	 Report
SF66.0110	Lens Maxi BGA for AVP4/4XL, f=16mm, 65*85mm	 Maxi-BGA AVP4
LW40.1097	Soldering nozzle set CSP/QFN (lead free)* for all CSP types, 4 pieces (9, 11, 13, 16)	 (length + 1.4 mm)
LW40.1099	Solder nozzle set BGA 7 for all (98%) types of BGA, 7 pieces	
LW01.0400	Soldering tool set SO (lead free)* for all SO...SOL...TSOP, 4 pieces	 (length + 1.4 mm)
LW01.0100	Soldering tool set QFP for all PLCC ...QFP, 7 pieces	
SF36.1002	PCB flex support 40.5 for HIF 09, "12 pin"	
SF03.0014	PCB magnet holder Easy Lock 40.5 (snap) for IR/IRD/IRH/IRF radiation element	 40.5
LWxx.xxx4	Reballing oven and masks for all types of BGA/CSP, your choice	
SF71.0001	Side Camera for ES 05, camera, stand, cable, DVD	
DB00.0025	Nitrogen input for DBL 04/05/06 (2.p.r) reduces consumption of N2 for vacuum	 N ₂
SF00.0028	Line connector CEE 32 A for HIF 08/09/10/IRF 07 with hints	